

BTA416Y-800B 3Q Hi-Com Triac

Rev.03 - 30 May 2023

**Product data sheet** 

### **1. General description**

Planar passivated high commutation three quadrant triac in a IITO220 internally insulated plastic package intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. This "series B" triac will commutate the full RMS current at the maximum rated junction temperature without the aid of a snubber. This device has high T<sub>j</sub> operating capability and an internally isolated mounting base.

### 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by dV/dt
- High surge capability
- High T<sub>j(max)</sub>
- Isolated mounting base with 2500 V (RMS) isolation
- · Least sensitive gate for highest noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- · Very high immunity to false turn-on by dV/dt

### 3. Applications

- Electronic thermostats (heating and cooling)
- High power motor controls
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

### 4. Quick reference data

Table 1. Q	uick reference data		 			
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Absolute	maximum rating					
$V_{\text{DRM}}$	repetitive peak off-state voltage		-	-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; T <sub>mb</sub> ≤ 108 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>	-	-	16	A
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 20 ms; <u>Fig. 4; Fig. 5</u>	-	-	160	A
		full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 16.7 ms	-	-	176	А
T <sub>j</sub>	junction temperature		-	-	150	°C
Static ch	aracteristics	·		_	-	
I <sub>GT</sub> (	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	2	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	2	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	2	-	50	mA

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.2	1.5	V
Dynamic	characteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	1000	-	-	V/µs
		$V_{DM}$ = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	600	-	-	V/µs
dl <sub>com</sub> /dt	rate of change of commutating current	$V_D = 400 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu \text{s}; \text{ (snubberless condition); gate open circuit}$	15	-	-	A/ms
		$V_D = 400 \text{ V}; \text{ T}_j = 150 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu \text{s}; \text{ (snubberless condition); gate open circuit}$	6	-	-	A/ms

# 5. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	N
2	T2	main terminal 2	$\neg$ $\downarrow \bigcirc \downarrow$	
3	G	gate		sym051
mb	n.c.	mounting base; isolated		

# 6. Ordering information

Table 3. Ordering information								
Type number	Package	Orderable part number	Packing	Small packing	Package	Package		
	Name		method	quantity	version	issue date		
BTA416Y-800B	IITO220	BTA416Y-800B,127	Tube	50	SOT78D (A)	10-July-2007		
					IITO220P (P)	31-Mar-2023		

# 7. Marking

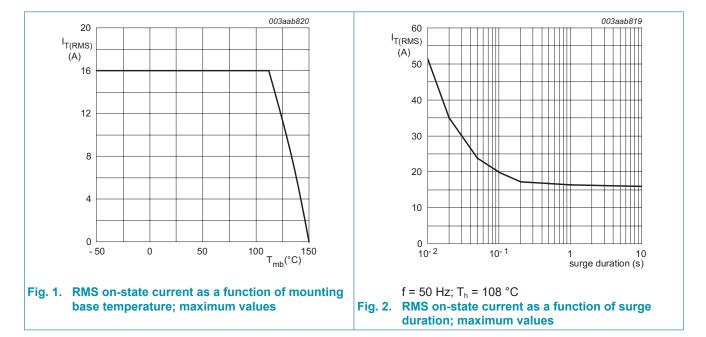
Table 4. Marking codes				
Type number	Marking codes			
	Assembly factory: A	Assembly factory: P		
BTA416Y-800B	BTA416Y 800B PJAxxxx xx	BTA416Y 800B PJPxxxx xx		

# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{\text{DRM}}$	repetitive peak off-state voltage		-	800	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>mb</sub> ≤ 108 °C; <u>Fig 1</u> ; <u>Fig 2</u> ; <u>Fig 3</u>	-	16	A
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 20 ms; Fig 4; Fig 5	-	160	A
		full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 16.7 ms	-	176	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>P</sub> = 10 ms; SIN	-	128	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 0.2 A	-	100	A/µs
I <sub>GM</sub>	peak gate current		-	4	А
$P_{GM}$	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	1	W
T <sub>stg</sub>	storage temperature		-40	150	°C
Tj	junction temperature		-	150	°C



#### BTA416Y-800B 3Q Hi-Com Triac

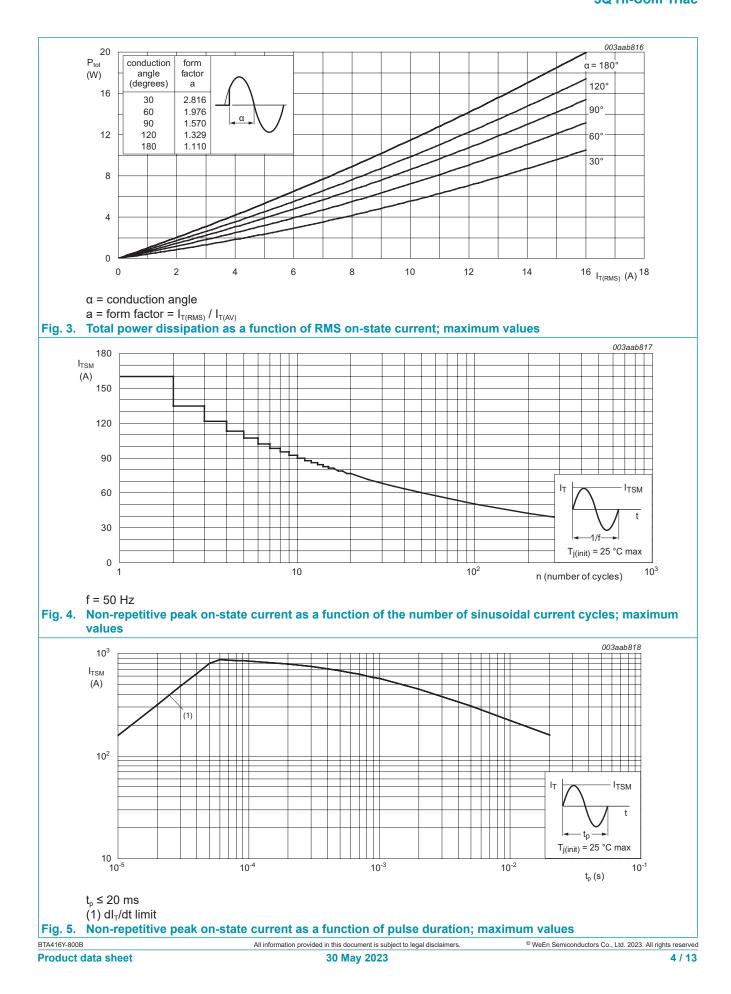
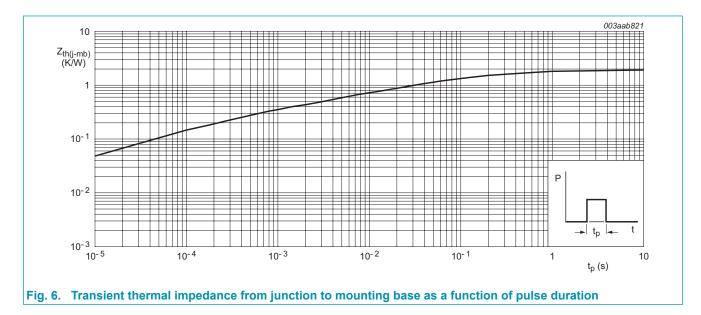


Table 6. Th	ermal characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th}(j\text{-}mb)}$	thermal resistance from junction to mounting base	full cycle; <u>Fig. 6</u>	-	-	1.9	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

### 9. Thermal characteristics



# **10. Isolation characteristics**

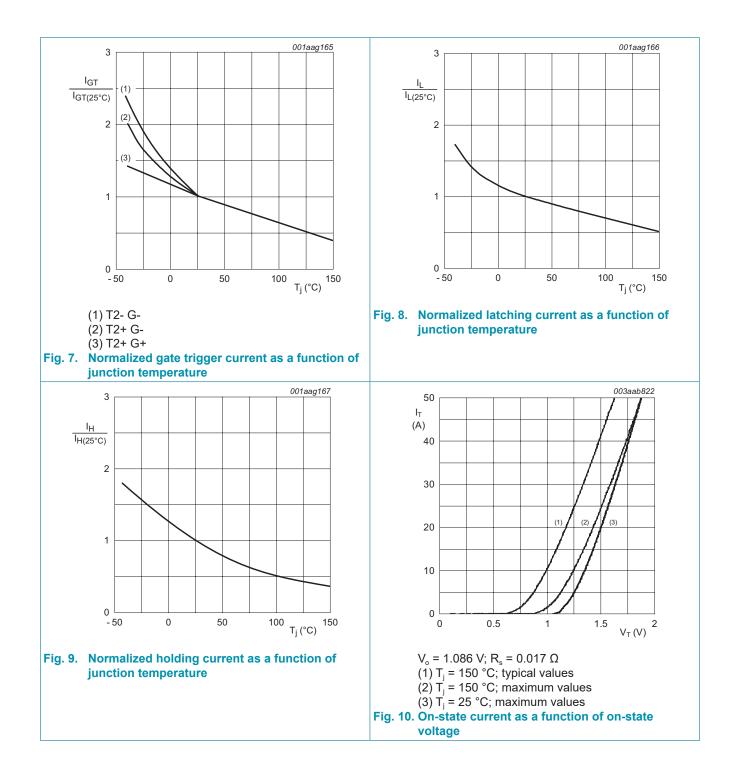
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{\text{isol}(\text{RMS})}$	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; T <sub>h</sub> = 25 °C	-	-	2500	V
$C_{\text{isol}}$	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; $T_h = 25 \degree C$	-	10	-	pF

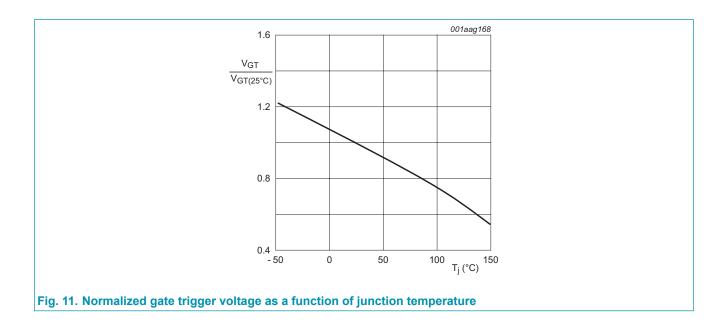
# **11. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics					
I <sub>GT</sub>	gate trigger current	$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T2+ G+};$ $\text{T}_{j} = 25 ^{\circ}\text{C}; \text{ Fig. 7}$	2	-	50	mA
		$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T2+ G-};$ $\text{T}_{j} = 25 ^{\circ}\text{C}; \text{ Fig. 7}$	2	-	50	mA
		$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T2- G-};$ $T_{j} = 25 \text{ °C}; \text{ Fig. 7}$	2	-	50	mA
I <sub>L</sub>	latching current	$V_{D} = 12 \text{ V}; \text{ I}_{G} = 0.1 \text{ A}; \text{ T2+ G+};$ $\text{T}_{j} = 25 ^{\circ}\text{C}; \text{ Fig. 8}$	-	-	60	mA
		$V_{D} = 12 \text{ V}; \text{ I}_{G} = 0.1 \text{ A}; \text{ T2+ G-};$ T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	-	90	mA
		$V_{D} = 12 \text{ V}; \text{ I}_{G} = 0.1 \text{ A}; \text{ T2- G-};$ T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	-	60	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.2	1.5	V
V <sub>GT</sub> gate t	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; Fig. 11	-	0.7	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 150 °C	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 125 °C	-	0.1	0.5	mA
		V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C	-	0.4	2	mA
Dynamic	characteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	1000	-	-	V/µs
		$V_{DM}$ = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	600	-	-	V/µs
	rate of change of commutating current	$V_{D} = 400 \text{ V}; \text{ T}_{j} = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu \text{s}; \text{ (snubberless condition); gate open circuit}$	15	-	-	A/ms
		$V_D = 400 \text{ V}; \text{ T}_j = 150 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu\text{s};  (snubberless condition); gate open circuit$	6	-	-	A/ms

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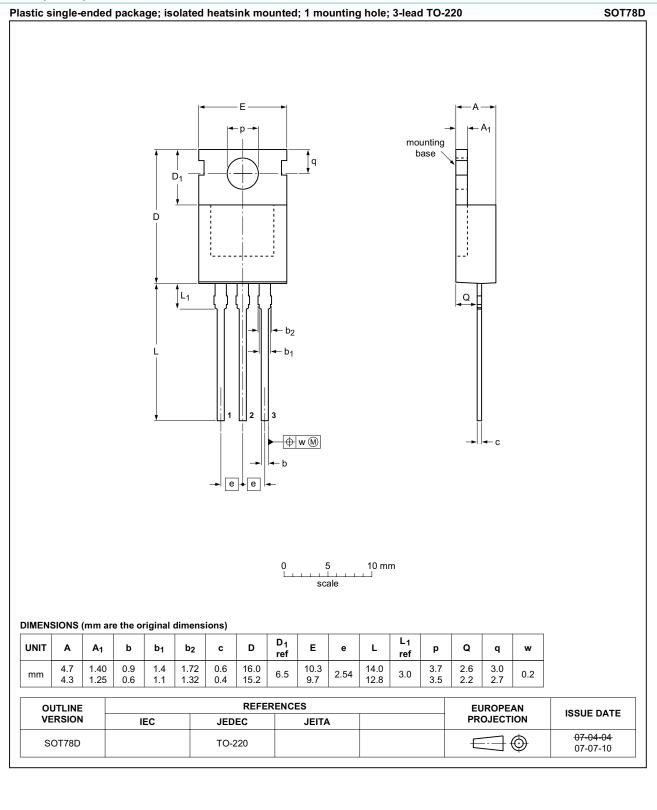
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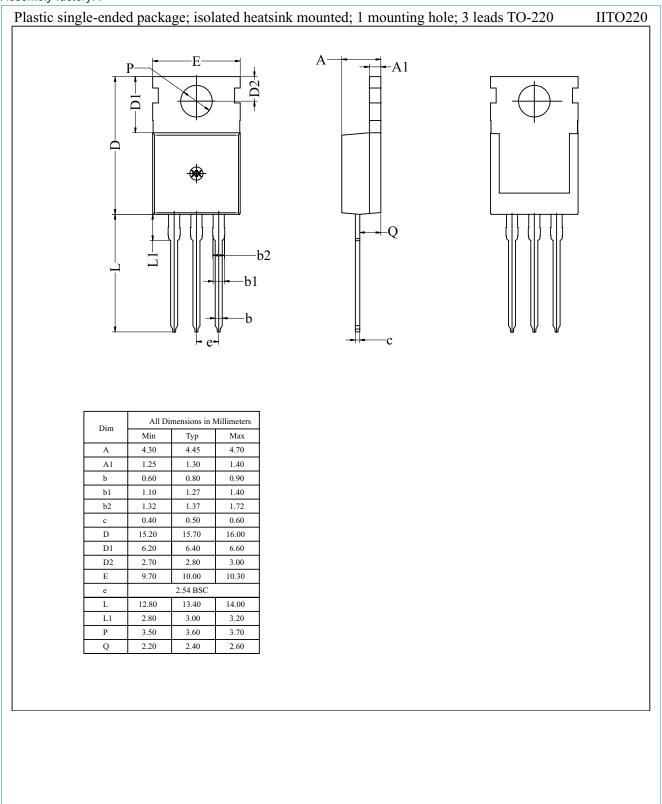


### 12. Package outline

#### Assembly factory: A



#### Assembly factory: P



# 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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